PROTOTYPING SUPPORT FUND UTILIZATION FORM

King Fahd University of Petroleum & Minerals

Technology Advancement & Prototyping Center (TAPC)

1. Title of your Research/Innovation Activity: _____

2. Please describe your Research/Technology Development/ Innovation:

*Note: Attach additional supporting document if deemed necessary

3. Status of your research/Innovation/Technology Development:

□ Basic Research □ Collaboration research with Industry □ Ideation Stage □ Concept Validation Stage □ Concept Development & Testing stage □ Prototyping Stage □ Product Development Stage □ Market Testing & Validation Stage □ Commercialization Stage

4. What services would you like to avail from TAPC:

□ 3D CAD Designing □ 3D Printing □ PCB Fabrication □ 3D Scanning □ Reverse Engineering □ Finishing/ Post-Processing □ Concept Validation (Research/Commercialization)

*Note: Please refer to **Appendix A** for list of materials and hardware available

5. Personal details:

Full Name:				
KFUPM ID:		🗆 KFUPM Employee 🗆 KFUPM Student		
KFUPM Dept./Center:		Dept Head/		
KFUPM Email Id:		Chairman Sign:		
Contact No.	Office:	Mobile:		
Signature:		Date:		

FOR TAPC OFFICE USE							
TAPC cost estimation for the service (Saudi Riyals):							
Program Director's Decision:	Approved	Not Approved					
Comments:							
Program Director's Signature:	Date:						

APPENDIX A

Materials available for FDM & FFF 3D Printing:									
□ ABS	\Box ASA		□ PC	DPC-A	ABS				
DPC-ISO		:	□ NYLON 6		ON 12		ON 12 CF		
🗆 ANTERO 800NA		ERO 840CN03	□ ULTEM 9085		EM 1010	□ ST-1	.30		
Materials available for SLA 3D Printing:									
Clear Resin	🗆 Black	< Resin	🗆 Tough Resin		🗆 White Resin				
Gray Resin	🗆 Casta	able Resin	Flexible Resin						
Materials available for PCB Fabrication:									
\Box FR4 single sided with 5 microns cladding \Box FR4 dou					double sided with 5 microns cladding				
\Box FR4 single sided with 18 microns cladding \Box FF			🗆 FR4	double sided with 18 microns cladding					
\Box FR4 single sided with 35 microns cladding \Box FR4			double sided with 35 microns cladding						
□ FR4 Flexible single sided with 5 microns cladding									
Electro-Mechanical Hardware:									
□ myRIO □ myRIO Kit			Embedded System I		lit	□ Robotics Kit			
□ Raspberry Pi □ Texas Instrun		nent board 🛛 🗆 Launch Pad board			□ Analog Discovery Kit				
Data Acquisition syst	Data Acquisition system CompactRIO			□ Smart Camera for Image Processing Applications					
□ RF system									
Hardware for Reverse Engineering:									
□ Handy scan Portable 3D Scanner □ Quality control and inspection □ Reverse engineering									

*Note: If the required hardware is not mentioned above, you can mention the hardware and its estimated cost in the detailed description document.